



INVESTOR CALL

# AUTOMOTIVE & INDUSTRIAL

September 2021





# DISCLAIMER

This document is provided by Soitec (the “Company”) for information purposes only.

The Company’s business operations and financial position are described in the Company’s 2020-2021 Universal Registration Document (which notably includes the 2020-2021 Annual Financial Report).

The Company’s 2020-2021 Universal Registration Document was filed with the AMF. The Universal Registration Document is available on the Company’s website in both French and English versions ([www.soitec.com](http://www.soitec.com), in section “Company - Investors - Financial Reports”).

Your attention is drawn to the risk factors described in Chapter 2.1 of the Company’s 2020-2021 Universal Registration Document.

This document contains summary information and should be read in conjunction with the 2020-2021 Universal Registration Document.

This document contains certain forward-looking statements. These forward-looking statements relate to the Company’s future prospects, developments and strategy and are based on analyses of earnings forecasts and estimates of amounts not yet determinable. By their nature, forward-looking statements are subject to a variety of risks and uncertainties as they relate to future events

and are dependent on circumstances that may or may not materialize in the future. Forward-looking statements are not a guarantee of the Company’s future performance.

The Company’s actual financial position, results and cash flows, as well as the trends in the sector in which the Company operates may differ materially from those contained in this document. Furthermore, even if the Company’s financial position, results, cash-flows and the developments in the sector in which the Company operates were to conform to the forward-looking statements contained in this document, such elements cannot be construed as a reliable

indication of the Company’s future results or developments.

The Company does not undertake any obligation to update or make any correction to any forward-looking statement in order to reflect an event or circumstance that may occur after the date of this document. In addition, the occurrence of any of the risks described in Chapter 2.1 of the Universal Registration Document may have an impact on these forward-looking statements.

This document does not constitute or form part of an offer or a solicitation to purchase, subscribe for, or sell the Company’s securities in any country whatsoever. This document, or any part thereof,

shall not form the basis of, or be relied upon in connection with, any contract, commitment or investment decision.

Notably, this document does not constitute an offer or solicitation to purchase, subscribe for or to sell securities in the United States. Securities may not be offered or sold in the United States absent registration or an exemption from the registration under the U.S. Securities Act of 1933, as amended (the “Securities Act”). The Company’s shares have not been and will not be registered under the Securities Act. Neither the Company nor any other person intends to conduct a public offering of the Company’s securities in the United States.

# 01

# SOITEC AT A GLANCE

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# FOCUSING ON 3 STRATEGIC MARKETS TO EXPAND OUR PRODUCTS PORTFOLIO

## MOBILE COMMUNICATIONS



### MAIN DRIVERS

- 5G mmW
- 5G sub-6 GHz
- Mobile infrastructure
- WiFi 6

### SOITEC PRODUCTS

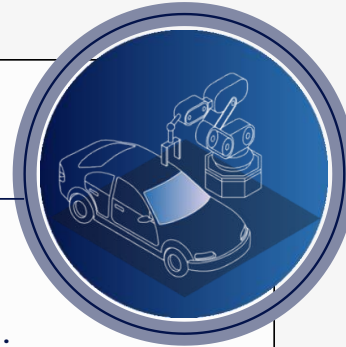
RF-SOI

FD-SOI

POI

GaN

## AUTOMOTIVE & INDUSTRIAL



### MAIN DRIVERS

- Autonomous cars
- Vehicle electrification
- Infotainment
- Industry 4.0

### SOITEC PRODUCTS

Power-SOI

FD-SOI

SiC

GaN

## SMART DEVICES



### MAIN DRIVERS

- Edge computing
- 3D sensing & Healthcare
- Smart home & Smart cities
- Data centers

### SOITEC PRODUCTS

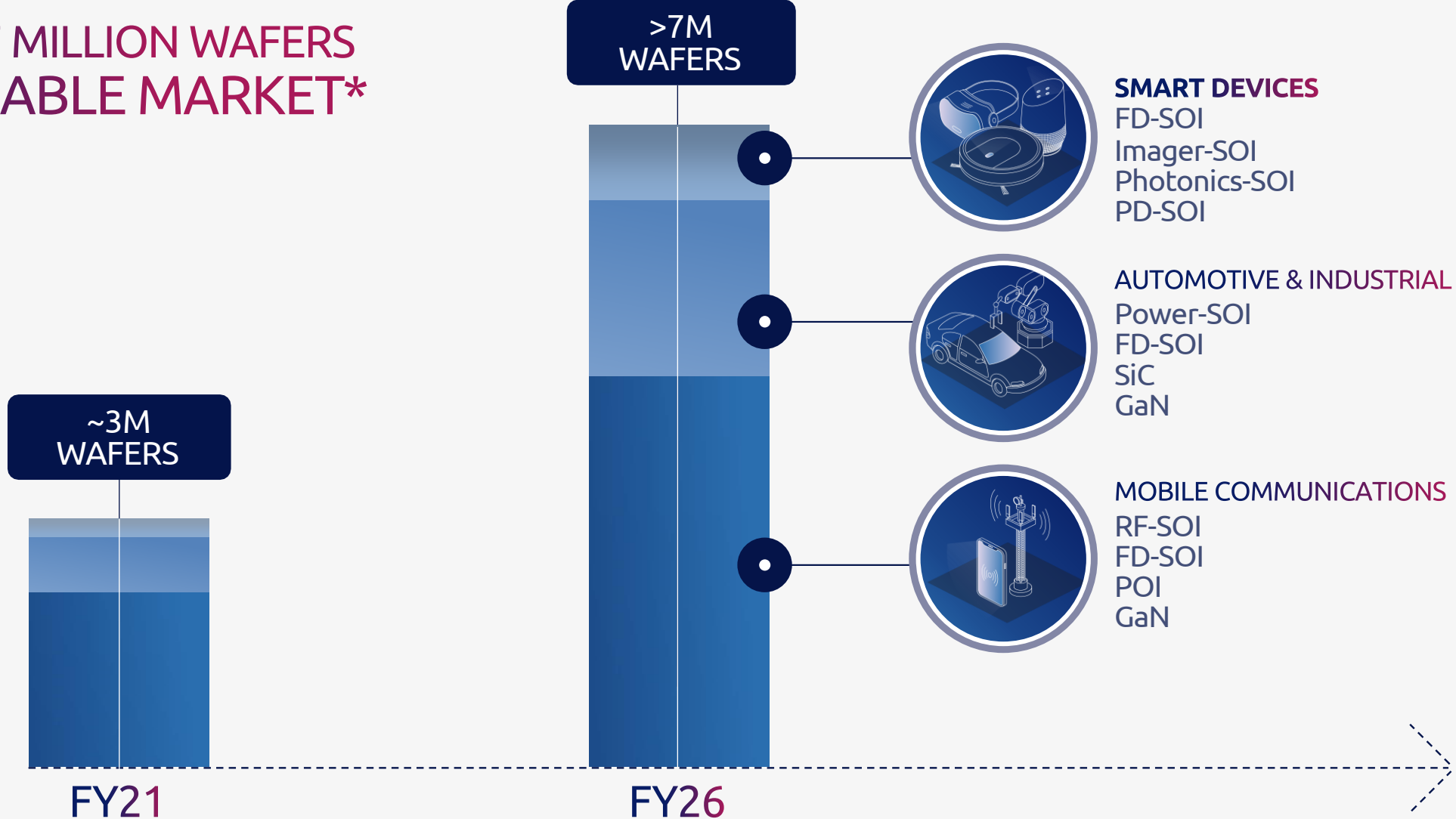
FD-SOI

Imager-SOI

Photonics-SOI

PD-SOI

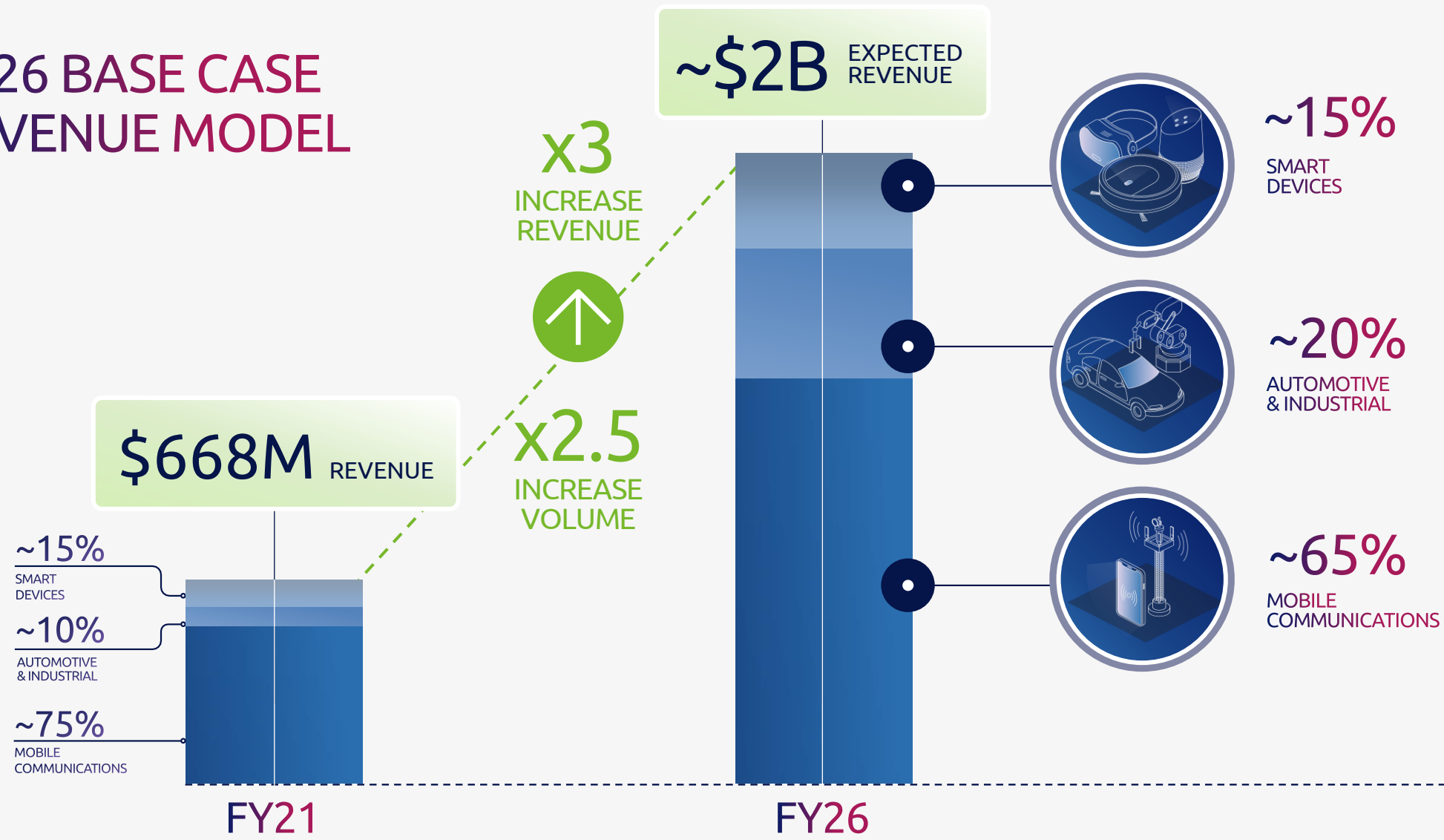
SERVING >7 MILLION WAFERS  
ADDRESSABLE MARKET\*  
BY FY26



\*Engineered substrates market opportunity

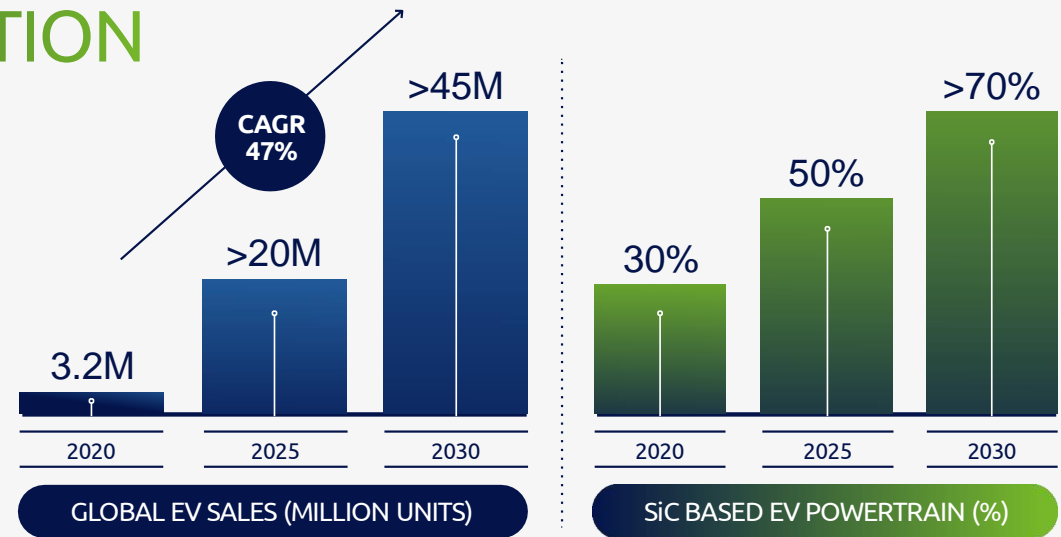
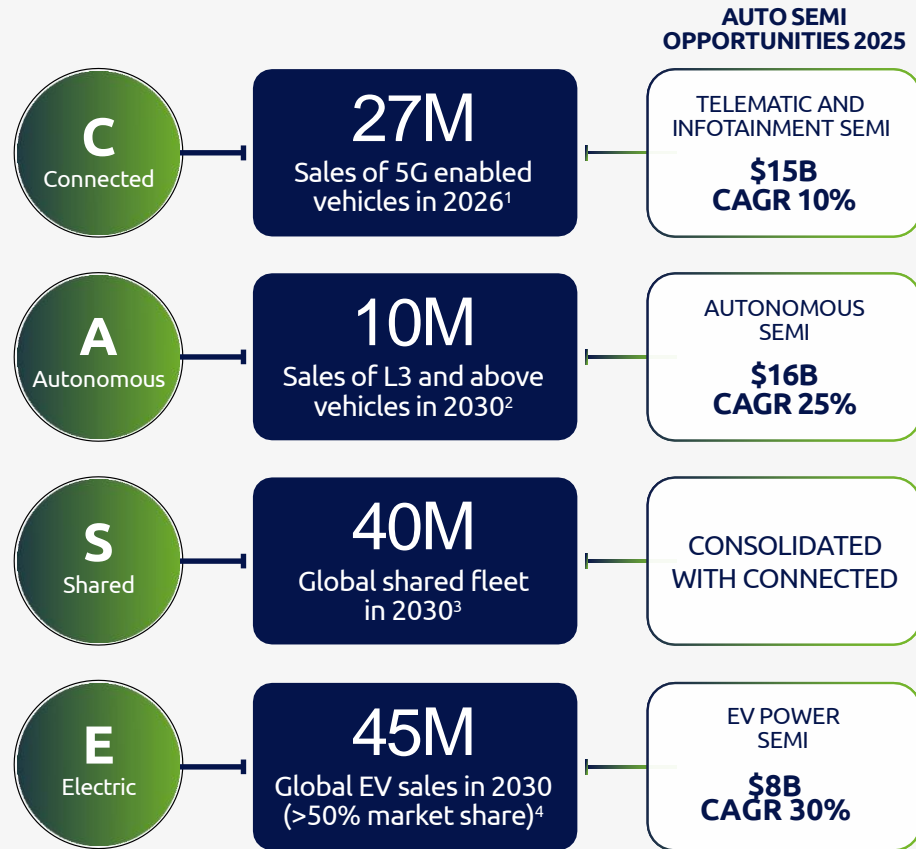


# FY26 BASE CASE REVENUE MODEL



# 02 AUTOMOTIVE & INDUSTRIAL

# ONCE-IN-A CENTURY TRANSFORMATION IN AUTOMOTIVE MARKET



**SiC IS KEY TO  
ADDRESS THE  
CHALLENGES OF  
EV ADOPTION**



Weight



Reliability



Thermal conductivity



Range anxiety



Charging time



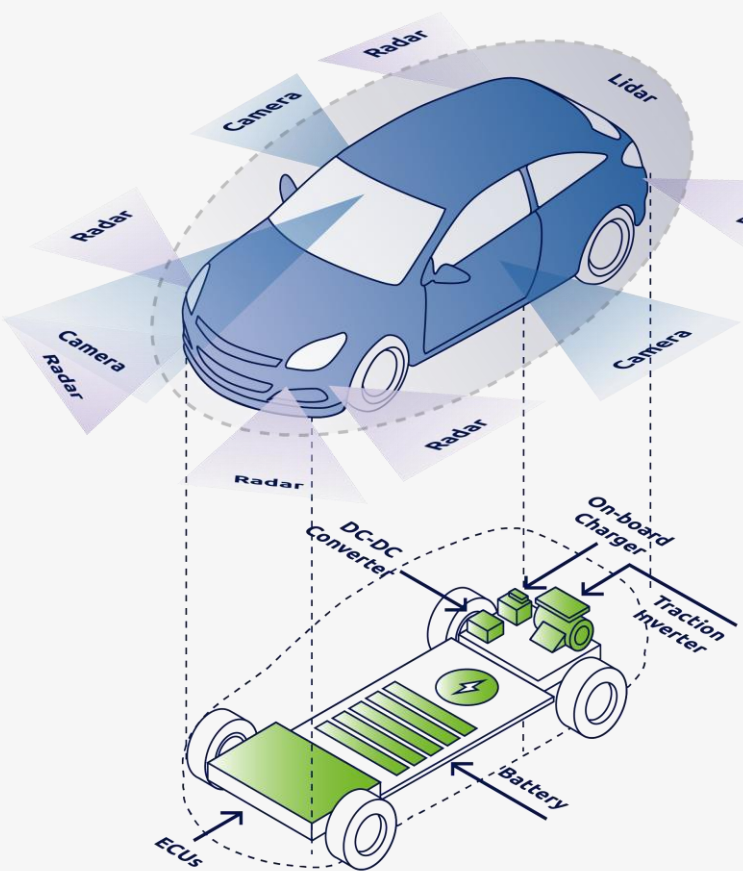
Cost

(1) v.s. 2020: Zero 5G vehicles; (2) v.s. 2020: Zero L3+ vehicles; (3) v.s. 2020: 19m global shared fleet; (4) v.s. 2020: 3.2m EV sales: 4.2% market share Sources: Soitec estimates, LMC, IHS, NXP, IFX 2019 / CAGR (2019~2025), IEA 2021, Exawatt, Yole.



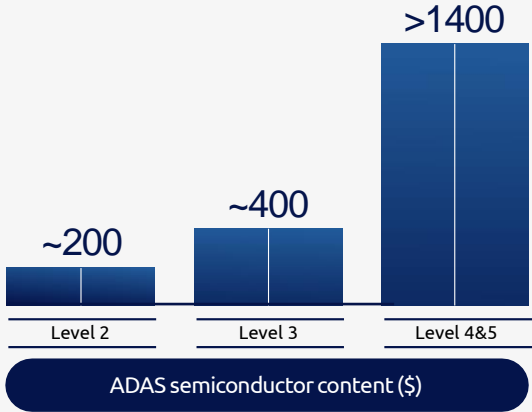
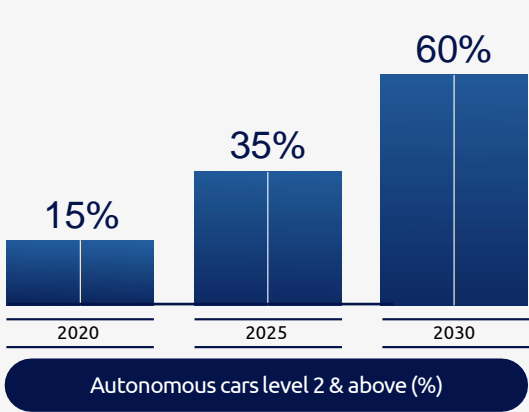
# AUTOMOTIVE MEGATRENDS

## DRIVE INNOVATION FROM SYSTEMS TO SILICON



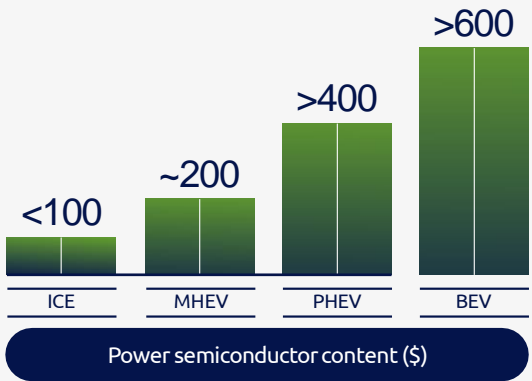
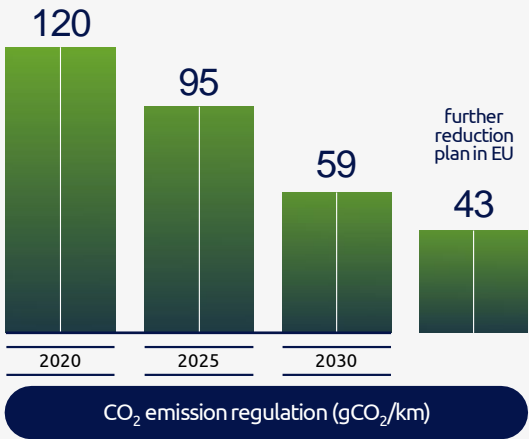
### ADAS

Fusion processor  
Radar processor  
Image sensor  
Domain controller



### ELECTRIFICATION

SiC Diode  
SiC MOSFET  
GaN MOSFET  
PMIC  
BMS  
Gate drivers  
Smart actuator



Source: Soitec estimates, Infineon, NXP, IHS, The International Council on Clean Transportation (ICCT) 2020



# SOITEC PRODUCTS PORTFOLIO AUTOMOTIVE & INDUSTRIAL

## APPLICATIONS

- Autonomous driving systems
- Connected car
- Vehicle electrification
- Industry 4.0



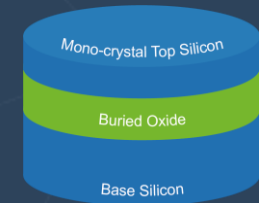
## SOITEC PRODUCTS ENABLE

- Autonomous driving
- Infotainment
- Vehicle electrification



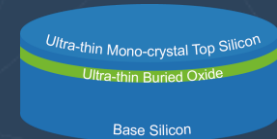
### Power-SOI

Power management ICs,  
In-vehicle networking  
& gate drivers



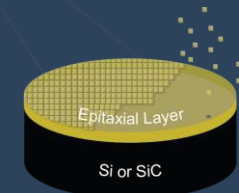
### FD-SOI

MCUs, ADAS-Radars  
ADAS-Vision



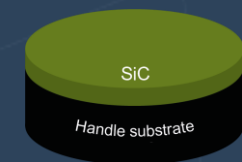
### GaN

DC-DC 48V converters



### Smart Cut™ SiC

Automotive  
electrification



# COMPREHENSIVE PRODUCTS PORTFOLIO FOR AUTOMOTIVE



## INFOTAINMENT & CONNECTIVITY

Class D audio amplifier  
(Power-SOI)

Multimedia application  
processor (FD-SOI)

IVN  
(Power-SOI)

Front-end module  
(RF-SOI / POI)

SoC  
(FD-SOI)



## ADAS

Vision processor  
(FD-SOI)

Radar  
(FD-SOI)

Domain controller  
(FD-SOI)



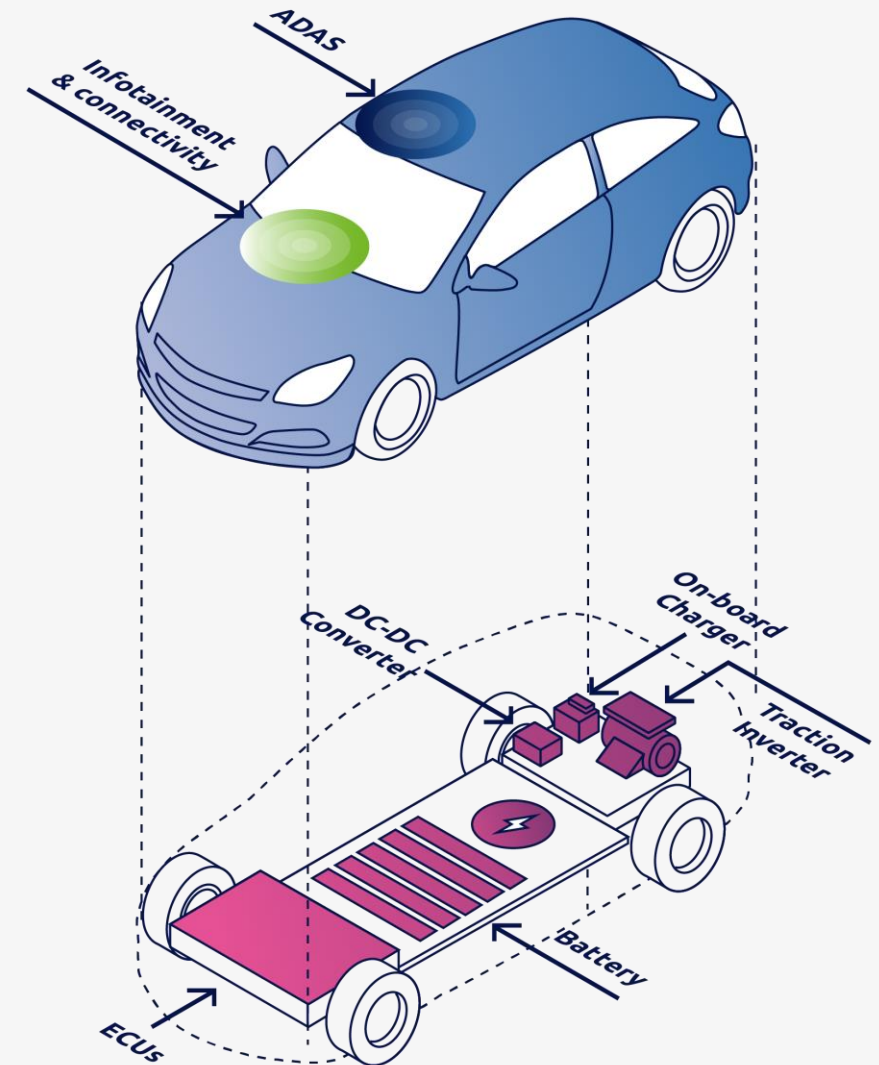
## POWERTRAIN

Gate drivers / actuator  
(Power-SOI)

Diode / MOSFET  
(SiC / GaN Power)

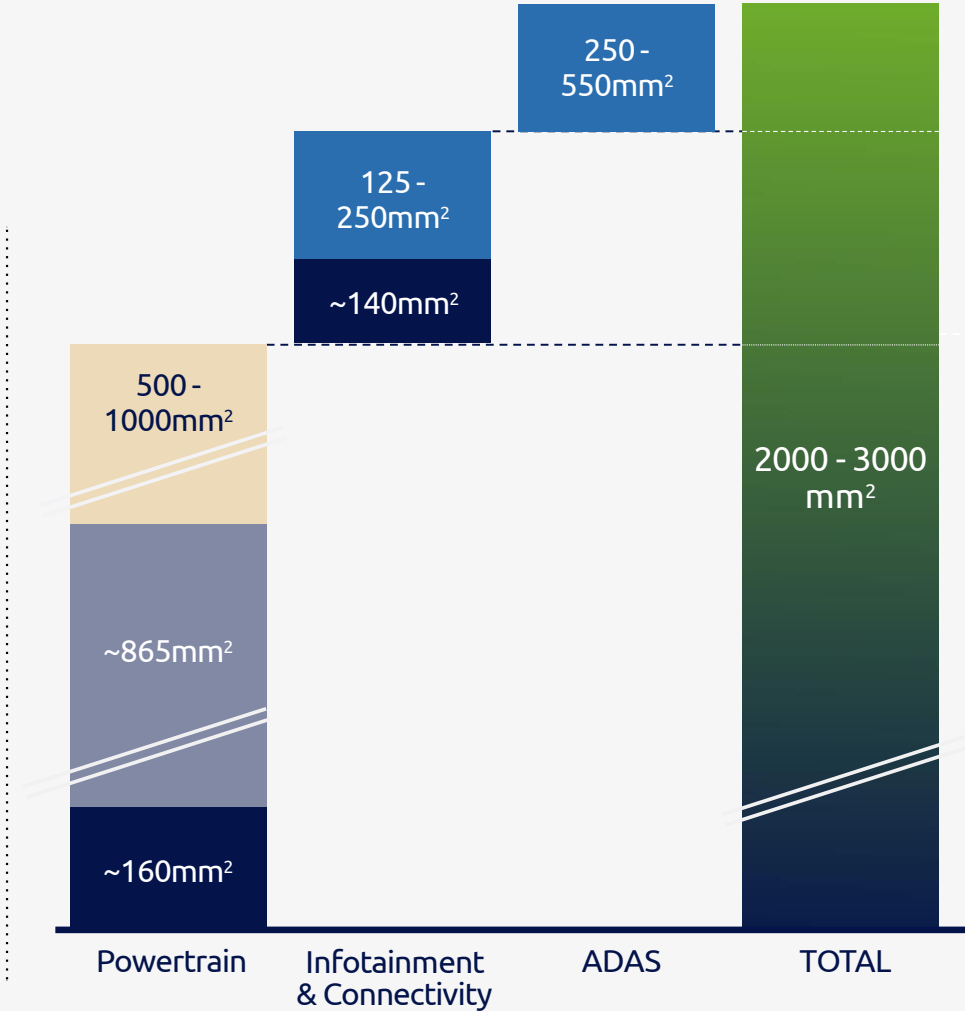
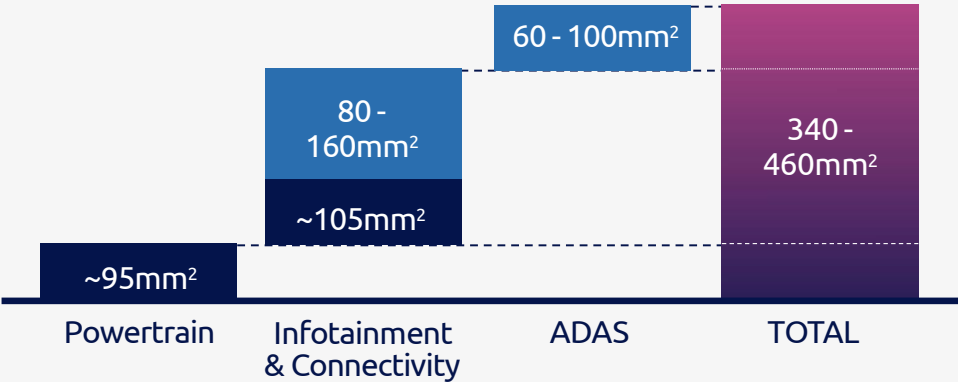
BMS  
(Power-SOI)

PMIC  
(Power-SOI)



# AUTOMOTIVE CONTENT OPPORTUNITY IN THE NEXT FIVE YEARS IN mm<sup>2</sup>

- Power-SOI
- FD-SOI
- Smart Cut™ SiC
- GaN



TODAY

WITHIN THE NEXT 5 YEARS

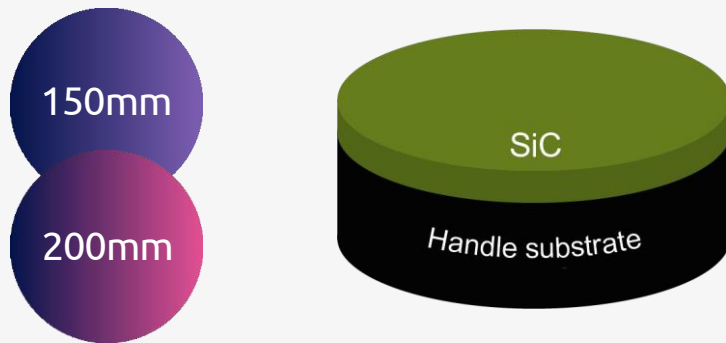


# 03

## SMART CUT™ SiC



# AUTOMOTIVE & INDUSTRIAL Smart Cut™ SiC



## EXISTING AND FUTURE APPLICATIONS

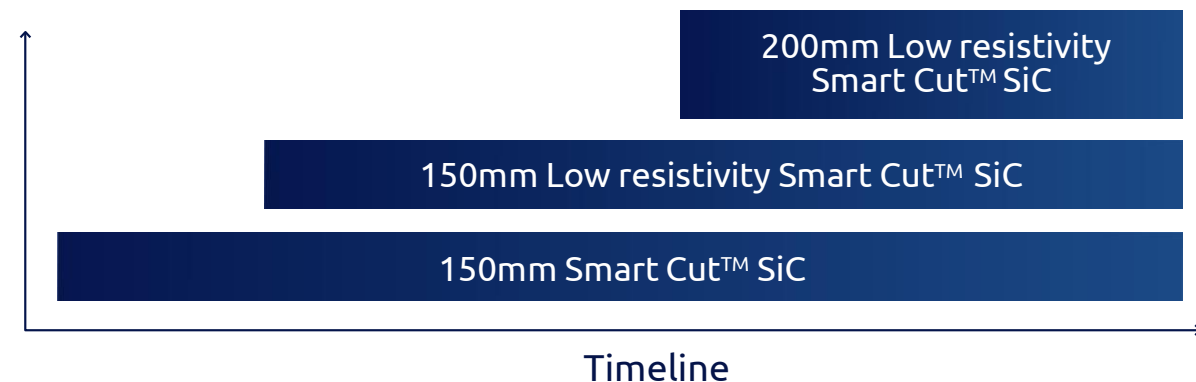
- Electric mobility
- On-board chargers
- Traction inverter system
- Fast charging stations
- Inverters: industrial, renewable energy

## VALUE PROPOSITION

Smart Cut™ SiC vs SiC: It is all about device yield and performances!

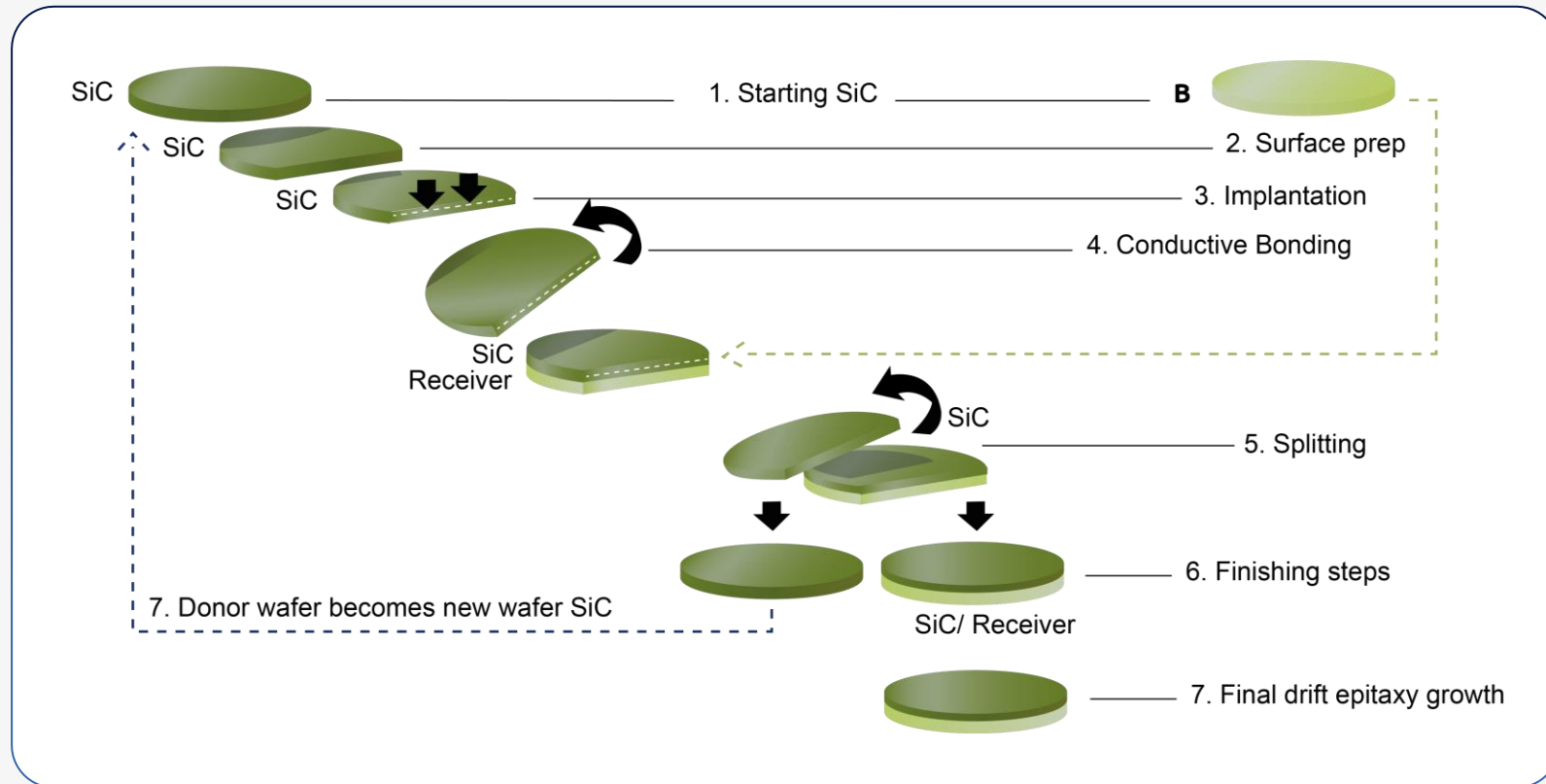
- Strong reduction of defect density (x5) to enable larger die
- Lower resistivity substrate improves device power performance
- 200mm scalability to accelerate SiC adoption

## FAMILY “SMART CUT SiC PRODUCT” ROADMAP FROM FY23



# SMART CUT™ PROCESS ADAPTED TO SiC

## FULL R&D PILOT LINE RUNNING



### MAJOR STAGES OF SMART CUT™ SiC

- Donor wafer: Prime quality SiC
- Handle wafer: Low Res SiC
- Conductive bonding interface
- Finishing including CMP & high temp anneal
- Donor wafer re-use for new process cycle

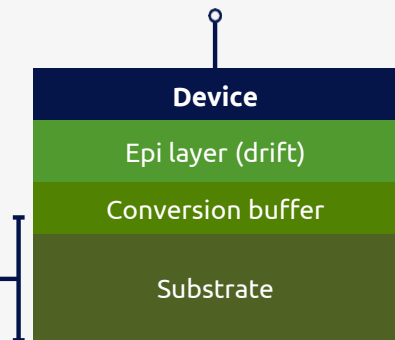
# SMART CUT™ SOLUTION

## SiC ENGINEERED SUBSTRATE

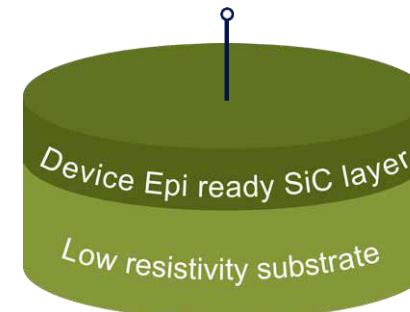
Current industry solution  
(monocrystalline bulk)



SiC Device structure



Smart Cut™'s engineered  
Epi-ready substrate solution



2021

Premium active layer



Epi-ready surface



SIMPLER PROCESS, HIGHER YIELD

2022

Lower base resistivity



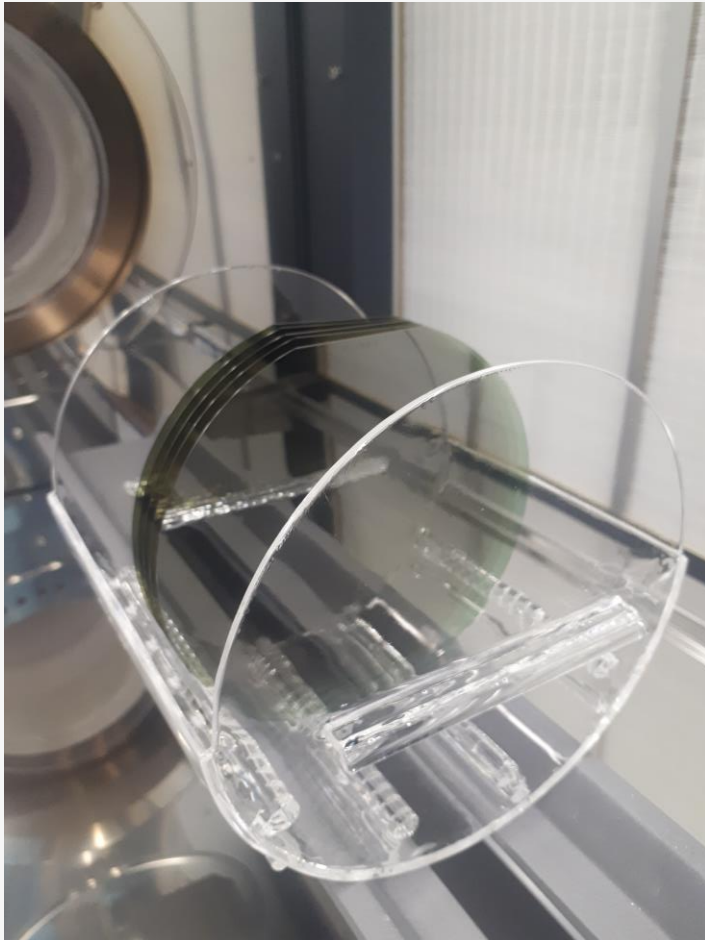
Lower losses at high current



SMALLER DIE, SYSTEM BENEFIT

# A GREENER SiC WAFER WITH SMART CUT™ TECHNOLOGY

Low environmental impact driven by...



Improved  
**RE-USABILITY**

**10x**

re-use of Bulk SiC donor

Lower  
**DIE SIZE**

**15%**

drives lower use of SiC material  
surface & lower power losses

Higher  
**YIELD**

**20%**

increase in the yield of devices  
with dimensions > 20mm<sup>2</sup>

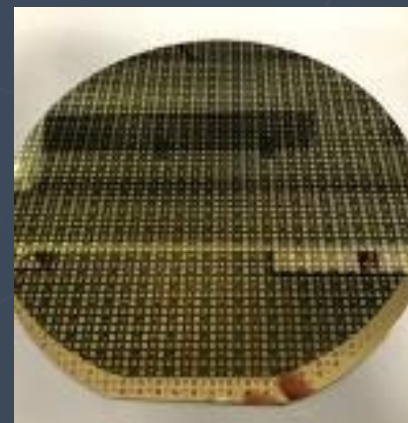
# 6-INCH ENGINEERED SiC SUBSTRATE



FROM SiC BULK



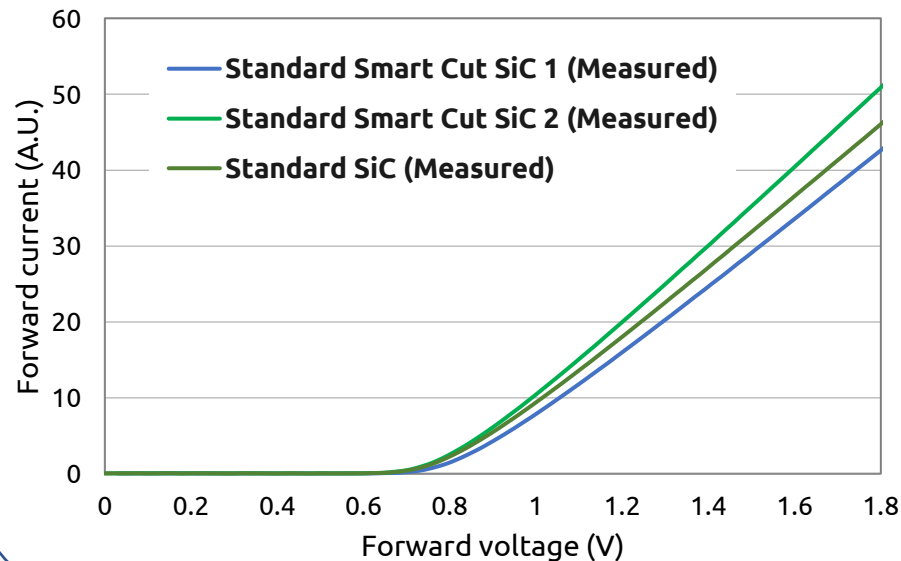
TO ENGINEERED  
SMART CUT™ SiC



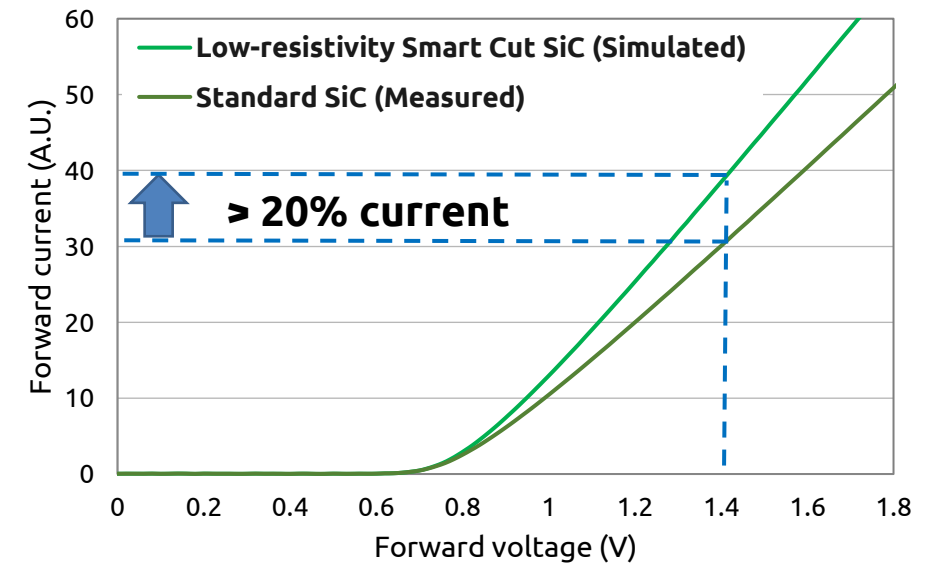
TO POWER  
DEVICES



# SMART CUT™ SiC DELIVERS SUPERIOR DEVICE PERFORMANCE



**Fully compatible with  
Schottky diode processing**

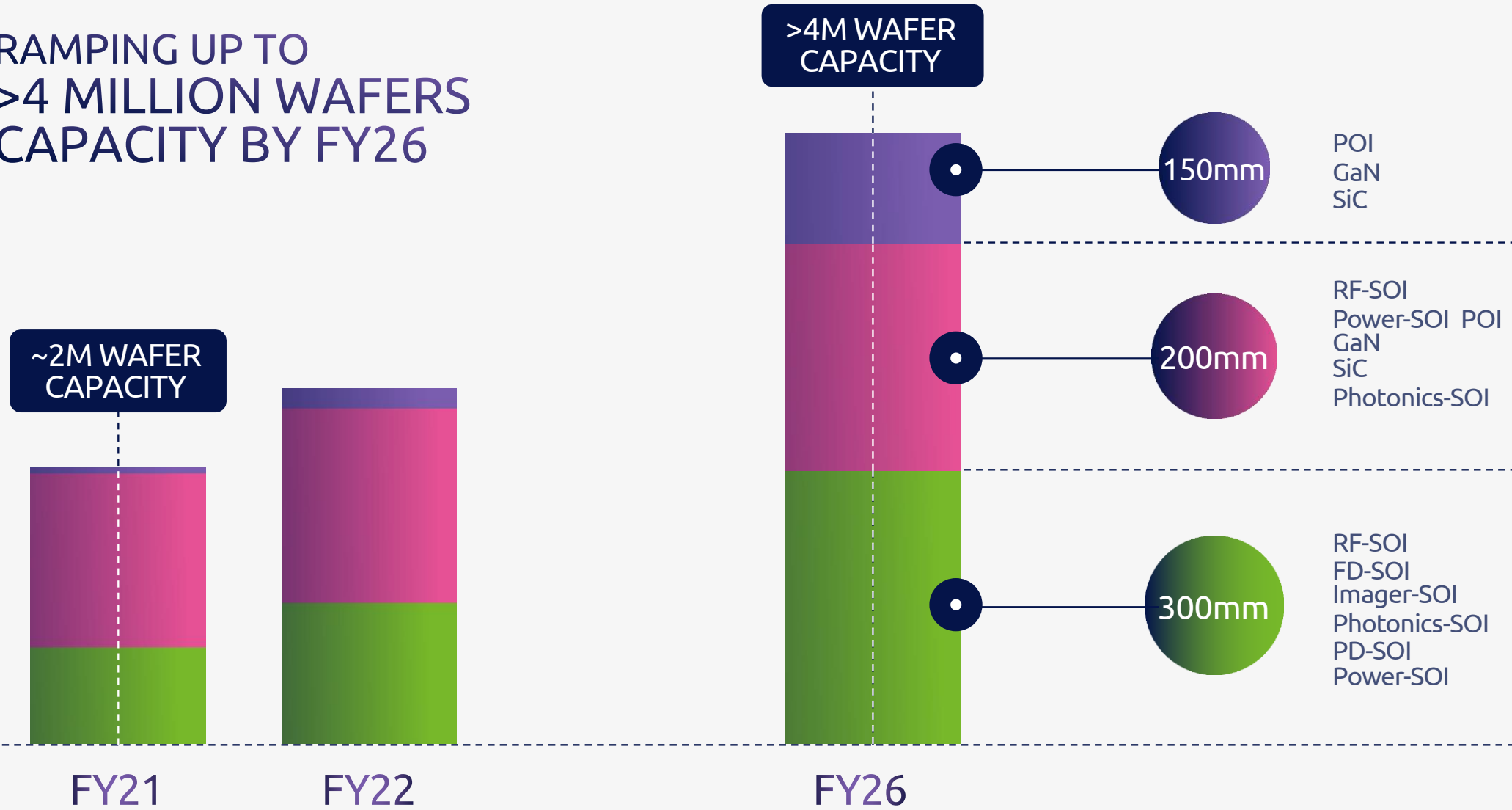


**Current gain up to 20%  
compared to standard SiC**

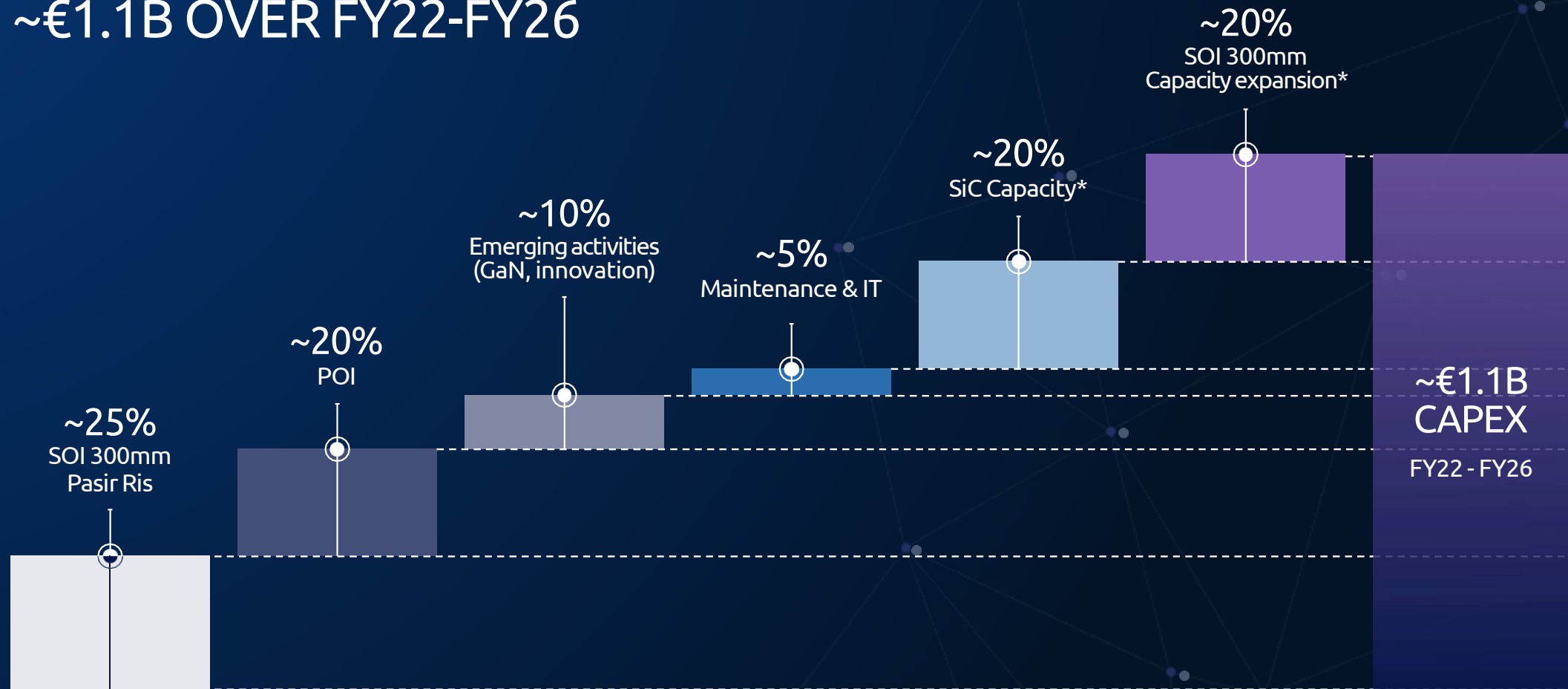
# APPENDIX

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# RAMPING UP TO >4 MILLION WAFERS CAPACITY BY FY26

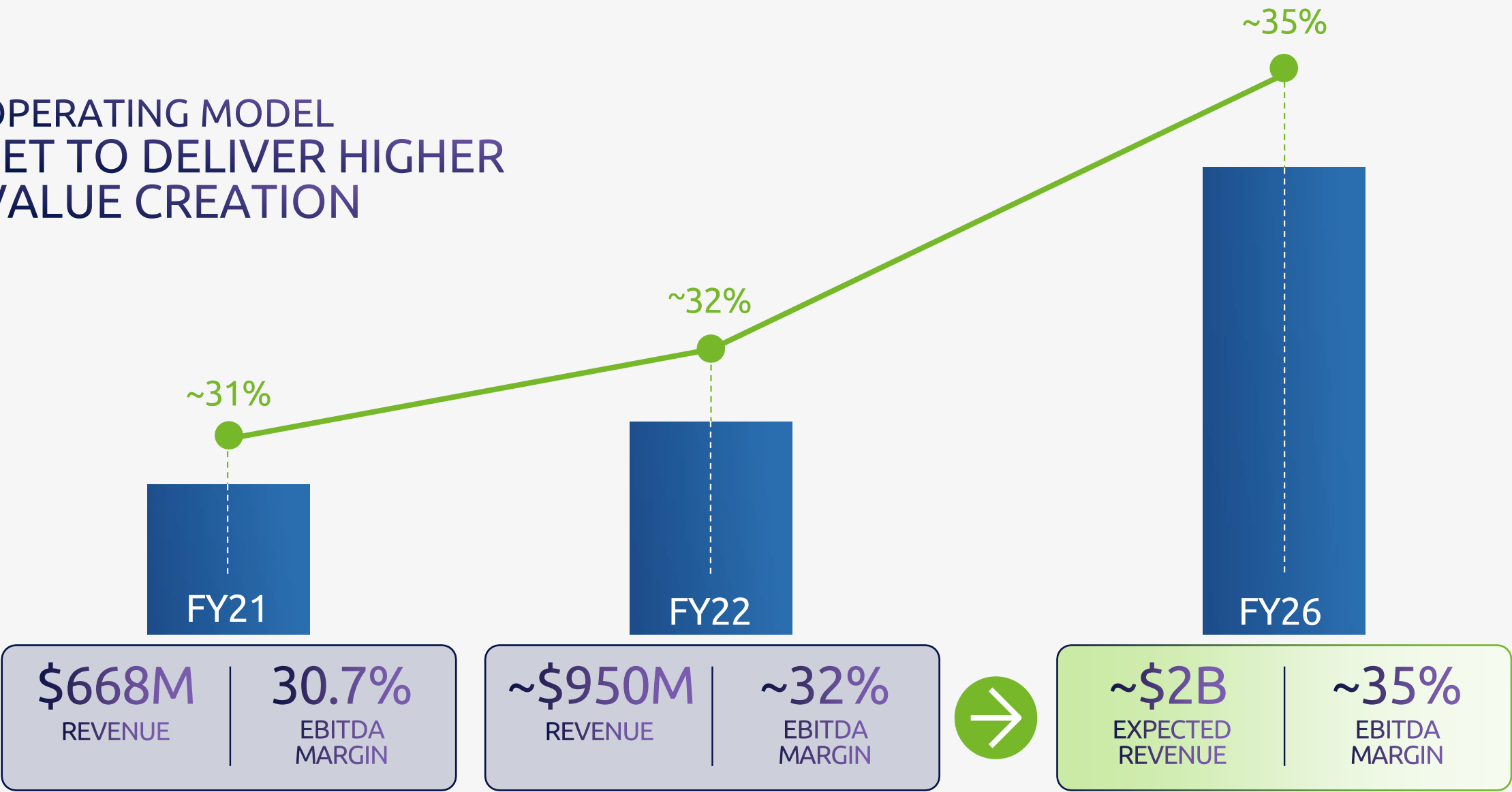


# CAPEX PLANS - ~€1.1B OVER FY22-FY26



(\*) Excluding capex for building

OPERATING MODEL  
SET TO DELIVER HIGHER  
VALUE CREATION



Note: Model estimates for FY26 using EUR/USD exchange rate at 1.20





# MID-TERM FINANCIAL MODEL

## REVENUE

- Revenue will more than triple between FY21 and FY26 to reach \$2B

## PROFITABILITY (@1.20 FX RATE)

- EBITDA in value more than x3 between FY21 and FY26
- CAPEX: around €1.1B between FY22 and FY26\*

## FINANCING

- Sufficient cumulative operating cash flows to finance CAPEX

	FY21 (Actual)	FY22	FY26 (Model)
<i>FX rate</i>	@1.13	@1.20	@1.20
Revenue (\$M)	668	~950	~2,000
Revenue (€M)	584	~800	~1,700
Gross margin %	31.4%	~34%	~36%
EBITDA % Revenue	30.7%	~32%	~35%
CAPEX % Revenue	24%	~30%	~18% over FY22-26



AUTOMOTIVE & INDUSTRIAL

THANK YOU